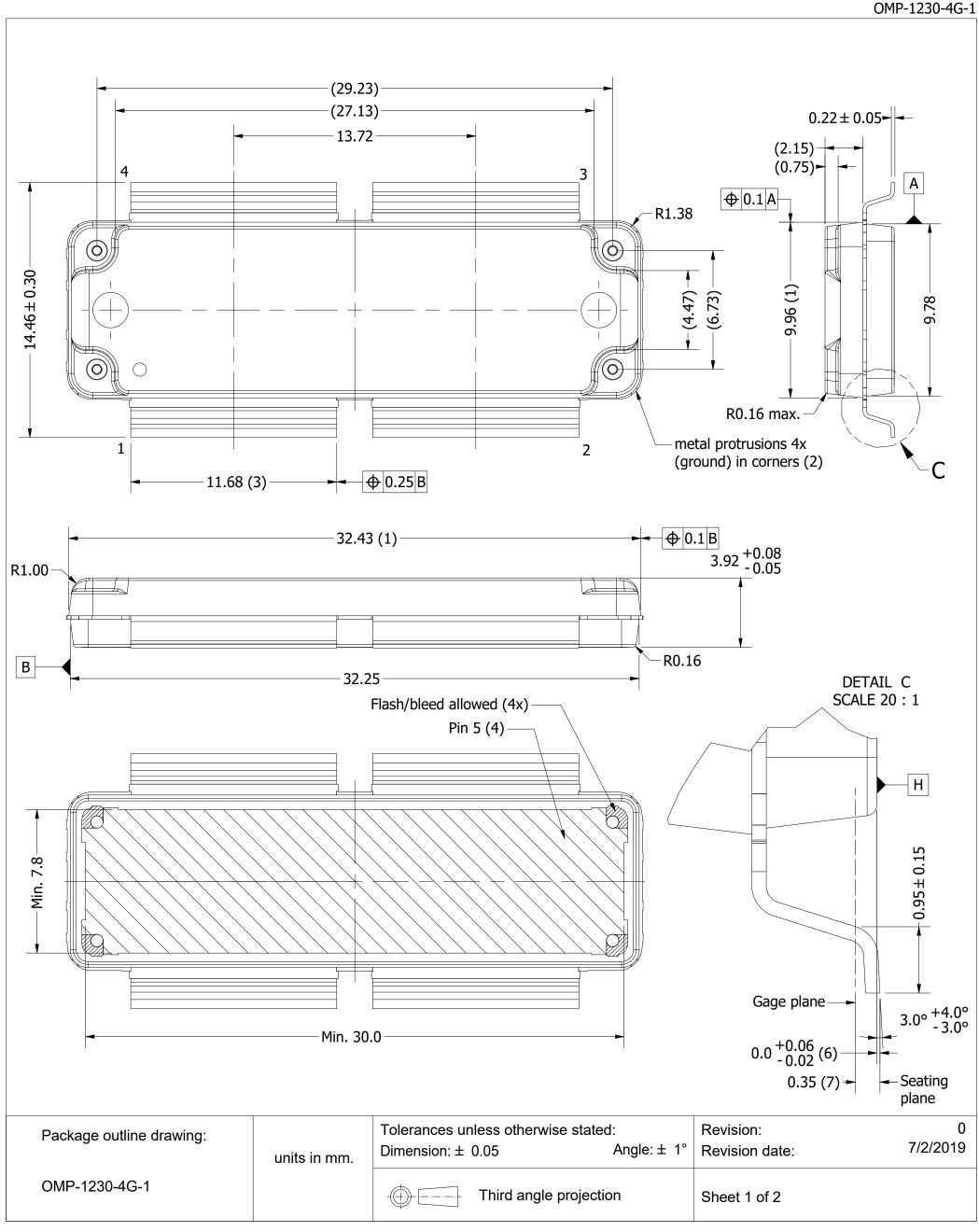
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Package outline

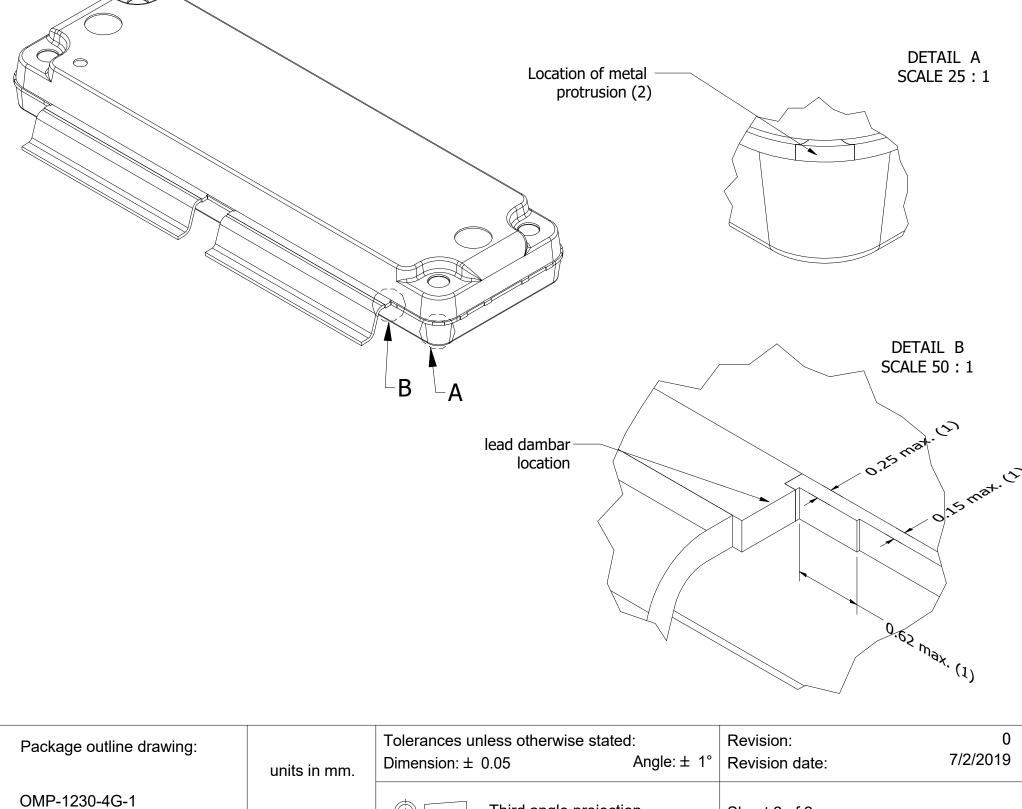




Package outline

OMP-1230-4G-1

| Drawing Notes | |
|---------------|---|
| Items | Description |
| | Dimensions are excluding mold protrusion. Areas located adjacent to the leads have a maximum mold protrusion of 0.25 |
| (1) | mm (per side) and 0.62 mm max. in length. At all other areas the mold protrusion is maximum 0.15 mm per side. See also |
| | detail B. |
| (2) | The metal protrusion (tie bars) in the corner will not stick out of the molding compound protrusions (detail A). |
| (3) | The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location. |
| (4) | The hatched area indicates the exposed metal heatsink. |
| (5) | The leads and exposed heatsink are plated with matte Tin (Sn). |
| (6) | Dimension is measured with respect to the bottom of the plastic package Datum H. Positive value means that the bottom of |
| (6) | the package is higher than the bottom of the lead. |
| (7) | Gage plane (foot length) to be measured from the seating plane. |



Third angle projection

Sheet 2 of 2